

Customer No.: 31561
Docket No.: 10/709,179
Application No.: 10544-US-PA

AMENDMENTS

FOR THE CLAIMS

Claims 1-14. Cancelled.

Claim 15. (Currently amended) A method of fabricating bumps on the backside of a chip, comprising the steps of:

providing the chip with an active surface having a plurality of at least a bonding pads thereon and the backside;

forming at least a bump pad on the backside of the chip; and

attaching forming a bump onto the bump pad.

Claim 16. (original) The method of claim 15, wherein the step of forming the bump pad on the backside of the chip further comprises:

forming a metallic layer on the backside of the chip; and

patterning the metallic layer to form the bump pad.

Claim 17. (original) The method of claim 15, wherein the step of forming the bump pad on the backside of the chip further comprises:

putting a mask on the backside of the chip, wherein the mask has at least an opening so that the backside of the chip is exposed;

forming a metallic layer over the mask and the exposed backside of the chip; and

removing the mask so that the remaining metallic layer on the backside of the

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chip becomes the bump pad.

Claim 18. (original) The method of claim 15, wherein before forming the bump pad on the backside of the chip, the method further comprises forming a protective film on the active surface of the chip.

Claim 19. (original) The method of claim 15, wherein the chip further comprises a passivation layer coated on the backside of the chip so that the passivation layer is removed before forming the bump pad on the backside of the chip.

Claim 20. (Currently amended) The method of claim 15, wherein during the step of forming the bump on attaching bumps to the bump pads, comprises performing one process selected from the group consisting of a patterning and electroplating process, a printing process, a bump-bonding process by a wire-bonding machine ~~or~~and a ball-implanting process are performed.